

ACDBAT320-HF Thru. ACDBAT3100-HF

Forward current: 3.0A

Reverse voltage: 20 to 100V

RoHS Device

Halogen Free

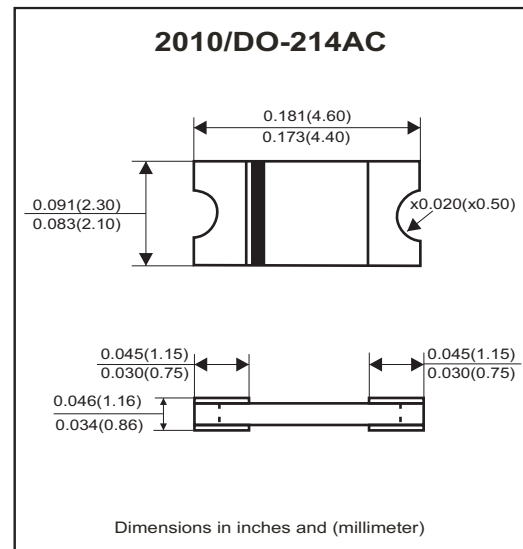


Features

- Lead less chip form, no lead damage.
- Low power loss, High efficiency.
- High current capability, low VF
- Plastic package has underwriters laboratory flammability classification 94V-0.
- Comply with AEC-Q101

Mechanical Data

- Case: Packed with FRP substrate and epoxy underfilled.
- Terminals: Pure Tin plated (Lead-Free), solderable per MIL-STD-750, method 2026.
- Polarity: Laser cathode band marking.
- Weight: 0.02 grams (approx).



Circuit Diagram



Maximum Ratings (At Ta=25°C, unless otherwise noted)

Parameter	Symbol	ACDBAT320-HF	ACDBAT340-HF	ACDBAT360-HF	ACDBAT3100-HF	Unit
Non-repetitive peak reverse voltage	V _{RM}	20	40	60	100	V
Average forward current	I _{F(AV)}	3				A
Peak forward surge current @8.3ms single half sine-wave	I _{FSM}	80				A
Operating junction temperature range	T _J	-55 to +125		-55 to +150		°C
Storage temperature	T _{STG}	-55 ~ +150				°C

Electrical Characteristics (At Ta=25°C, unless otherwise noted)

Parameter	Conditions	Type	Symbol	Min.	Typ.	Max.	Unit
Forward voltage (Note1)	$I_F=1.0A$	ACDBAT320-HF	V_F	-	0.37	-	V
	$I_F=3.0A$	ACDBAT340-HF		-	0.46	0.50	
	$I_F=1.0A$	ACDBAT360-HF		-	0.42	-	
	$I_F=3.0A$	ACDBAT3100-HF		-	0.58	0.70	
Reverse peak reverse current	$V_R=Max. V_{RRM}, T_a=25^\circ C$		I_{RRM}	-	0.02	0.2	mA
Junction capacitance	$V_R=4V, f=1.0MHz$		C_j	-	120	-	pF
Thermal resistance	Junction to ambient (Note 2)		$R_{\theta JA}$	-	86	-	°C/W
	Junction to lead (Note 2)		$R_{\theta JL}$	-	24	-	°C/W

Notes: (1) Pulse test width $p_w=300\mu sec$, 1% duty cycle.

(2) Mounted on P.C. board with 0.2×0.2 (5.0*5.0mm) copper pad areas.

Company reserves the right to improve product design , functions and reliability without notice.

REV:A

RATING AND CHARACTERISTIC CURVES (ACDBAT320-HF Thru. ACDBAT3100-HF)

Fig.1- Typical Forward Current Derating Curve

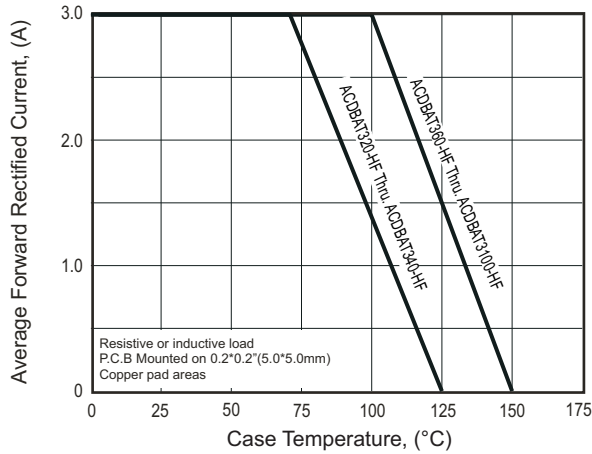


Fig.2- Maximum Non-Repetitive Peak Forward Surge Current

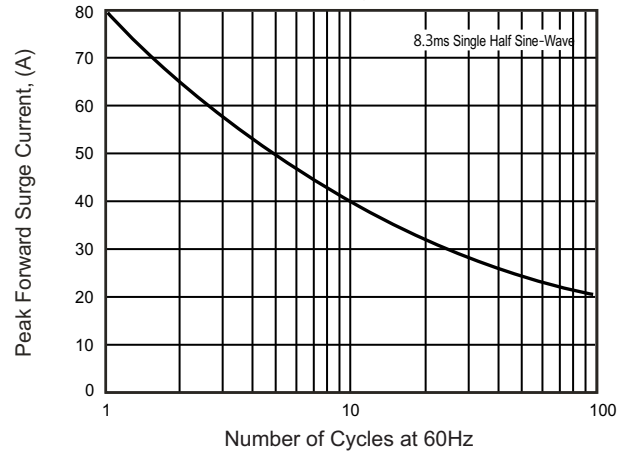


Fig.3- Typical Instantaneous Forward Characteristics

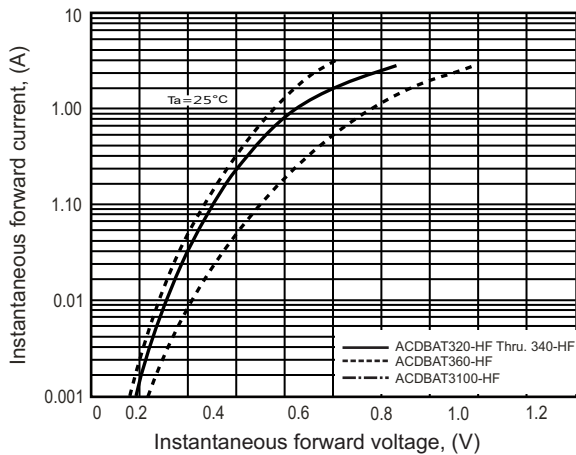


Fig.4- Typical Reverse Characteristics

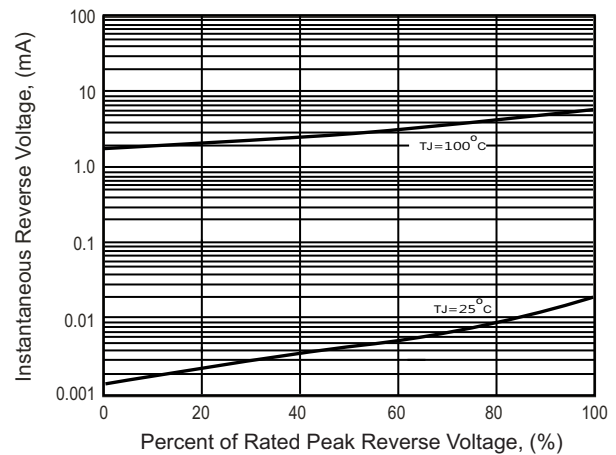
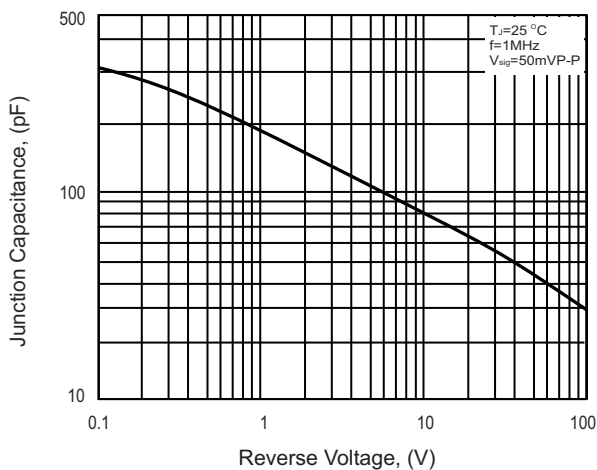
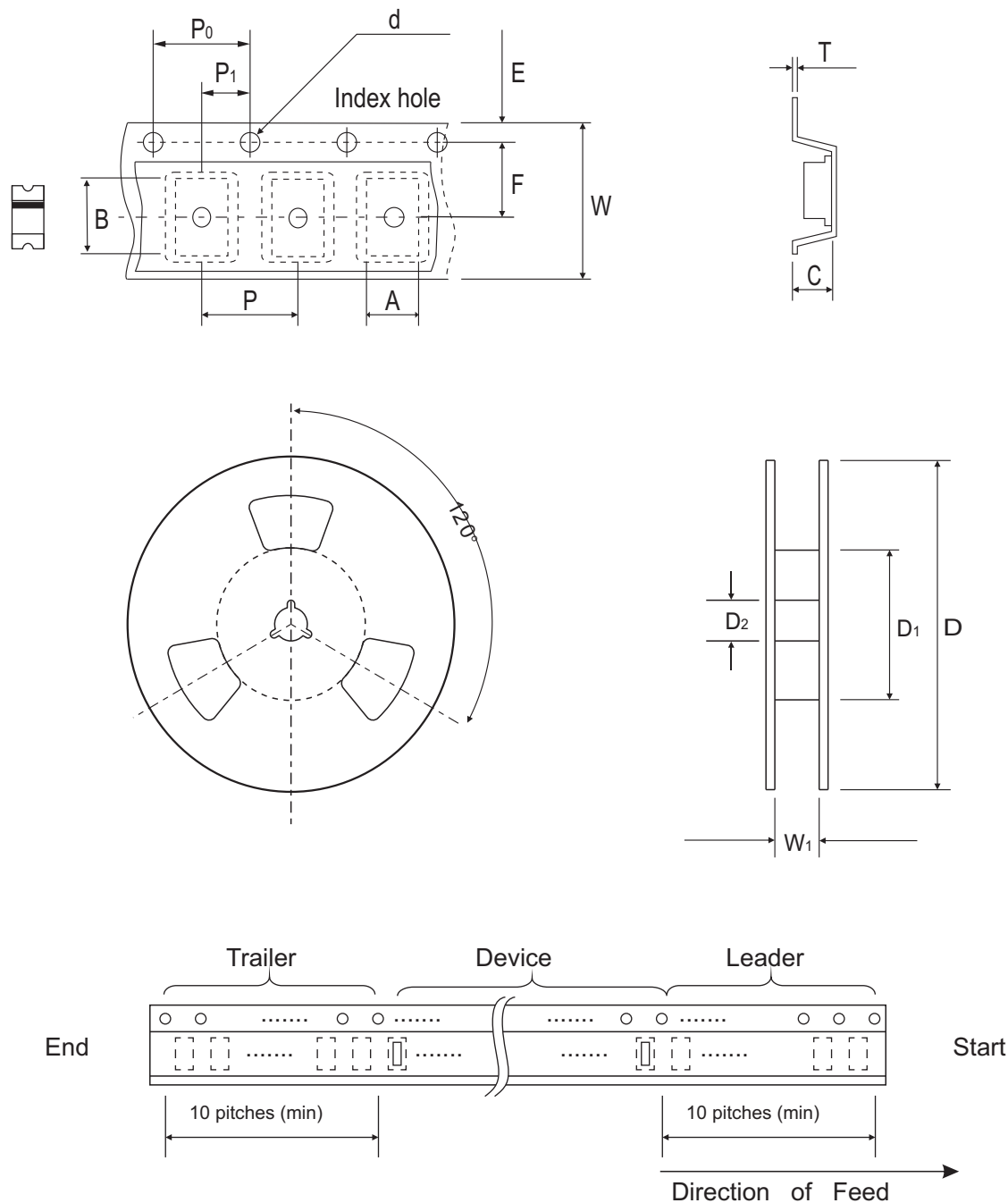


Fig.5- Typical Junction Capacitance



Reel Taping Specification



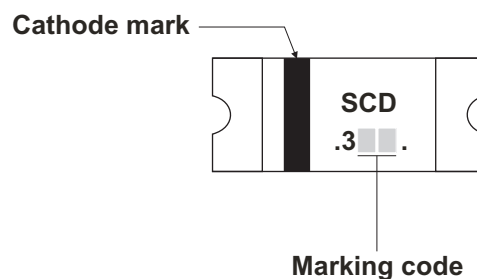
2010 (DO-214AC)	SYMBOL	A	B	C	d	D	D ₁	D ₂
	(mm)	4.70 ± 0.10	2.40 ± 0.10	1.26 ± 0.10	1.50 ± 0.10	330 ± 2.00	50.0 MIN.	13.0 ± 0.50
	(inch)	0.185 ± 0.004	0.094 ± 0.004	0.050 ± 0.004	0.059 ± 0.004	12.992 ± 0.079	1.969 MIN.	0.512 ± 0.020

2010 (DO-214AC)	SYMBOL	E	F	P	P ₀	P ₁	W	W ₁
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	12.00 ± 0.30	14.4 MAX.
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.472 ± 0.012	0.567 MAX.

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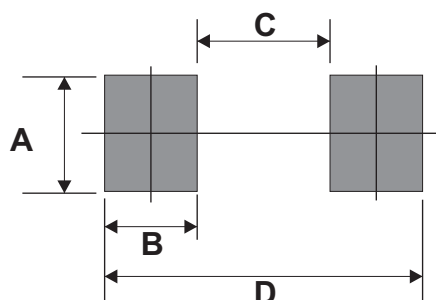
Marking Code

Part Number	Marking Code
ACDBAT320-HF	2
ACDBAT340-HF	4
ACDBAT360-HF	6
ACDBAT3100-HF	10



Suggested PAD Layout

SIZE	2010/DO-214AC	
	(mm)	(inch)
A	1.47MIN.	0.058MIN.
B	1.27MIN.	0.050MIN.
C	2.60MAX.	0.102MAX.
D	5.14REF.	0.202 REF.



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
2010/DO-214AC	3,000	7

Mouser Electronics

Authorized Distributor

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